



**PATENT APPLICATION**

Sheet 1 of 1

FORM PTO-1449

**LIST OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION DISCLOSURE  
STATEMENT**

(Use several sheets if necessary)

**ATTY. DOCKET NO.**

**SERIAL NO.**

10031071-1

Donald E. Schott et al.

**FILING DATE**

1/30/04

GROUP

Dark 2800

## **REFERENCE DESIGNATION**

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	*	DOCUMENT NUMBER	DATE	NAME
<i>NB</i>		6,108,212	8/22/00	Lach, et al.
<i>MJ</i>		6,132,543	10/17/00	Mohri, et al.

## **FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	NAME	TRANSLATION	
					YES	NO

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

NH	X	Tongbi Jiang, et al., Composite Interposer For BGA Packages, US2003/0164556 A1 Published 9/4/2003.
NH	X	Binng Y. Lao, et al., Single And Multiple Layer Packaging Of High-Speed/High-Density ICS, US2003/0096447 A1 published 5/22/03.
NH	X	Chung Wen Ho, High Density Cavity-Up Wire Bond, US2001/0046725 A1 Published 11/29/01.

**EXAMINER**

INNER  
Mun J mi

**DATE CONSIDERED**

F-16-08

\* Copies of these references are not enclosed pursuant to 37 CFR 1.98(d). (See accompanying IDS)